TEXAS INSTRUMENTS **12500 TI Boulevard, MS 8640, Dallas, Texas 75243**

PCN Number:	**20261021001.1**	**PCN Issued**	October 23, 2026
Qualification of TI Philippines (PHI) as an additional Assembly site for Select Devices		**Sample request deadline:**	December 22, 2026
		Estimated 1st ship date:	January 21, 2027
***Sample requests received after** December 22, 2026* **will not be supported.**			

Change type(s)
Assembly Site Assembly Process Assembly Material Packing/Shipping/Labeling

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Philippines (PHI) as an additional Assembly site for the devices listed below in the product affected section.

	Current site	**Additional site**
Assembly site	HFTF	PHI
Wire diam/type	0.8mil Au	0.8mil Cu
Mold compound	SID#R-27	4222198
MSL level	3	1
Marking difference	Binary	Secondary/ Binary

Qual details are provided in the Qual Data Section.

Reason for Change:	Supply continuity

Anticipated impact on Form, Fit, Function, Quality or Reliability:	Request the Supporting Data Packet for more details on the changes

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	**REACH**	**Green Status**	**IEC 62474**
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

Assembly Site Information

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
HFTF	HFT	CHN	Hefei
PHI	**PHI**	**PHL**	**Baguio City**

	Sample product shipping label (not actual product label): 

Products Affected:		
TMAG5110A2AQDBVR	TMAG5110C2AQDBVR	TMAG5111B2AQDBVR
TMAG5110B2AQDBVR	TMAG5111A2AQDBVR	TMAG5111C2AQDBVR

Qualification Summary

Approve Date 29-September-2026

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: TMAG5110B2AQDBVR	QBS Package Reference: TPS76933DBVR	QBS Package Reference: TLV9051QDBVRQ1	QBS Package Reference: INA299A3QDBVRQ1	QBS Package Reference: INA299A1IDBVR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	QBS	-	1/77/0	1/77/0	1/77/0
UHAST	A3	Autoclave	121C/15psig	96 Hours	QBS	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	QBS	-	-	1/77/0	1/77/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	QBS	3/231/0	-	3/231/0	1/77/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	QBS	3/231/0	-	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes); PB-Free Solder;	-	QBS	1/22/0	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	QBS	-	1/10/0	1/10/0	-
MQ	-	Assembly MQ	Per site specification	-	Pass	Pass	Pass	Pass	Pass

QBS: Qual By Similarity, also known as Generic Data
Qual Device TMAG5110B2AQDBVR is qualified at MSL1 260C
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
TI Qualification ID: R-CHG-2609-040

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these

industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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